

The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements

A

B

C

D

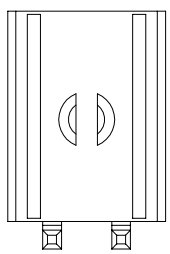
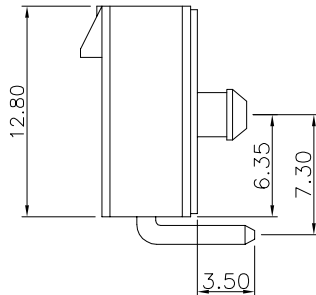
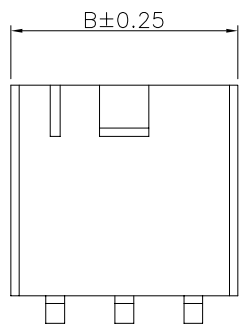
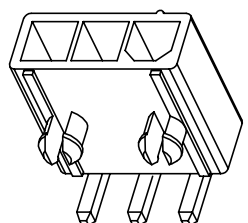
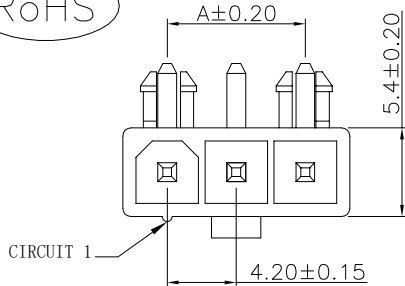
E

F

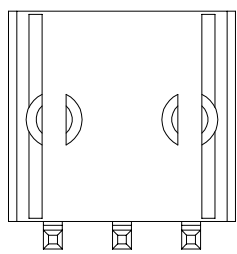
G

H

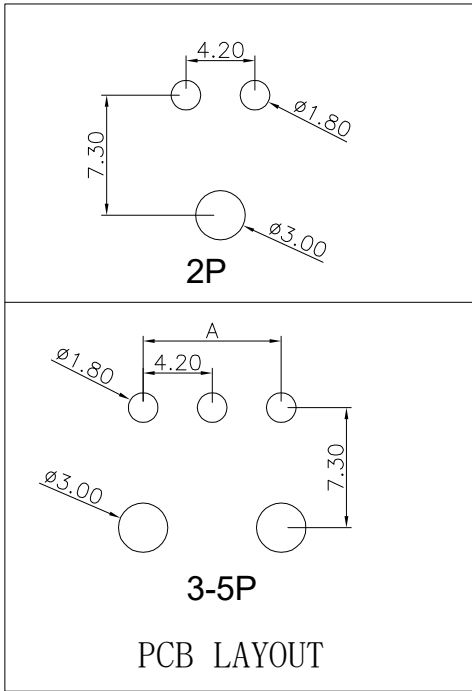
RoHS



2P



3-5P



Ordering Information & Dimensions

Circuit	Dimensions (mm)	
	A	B
02	4.20	9.60
03	8.40	13.80
04	12.60	18.00
05	16.80	22.20

- NOTE:
- 1.MATERIAL SPECIFICATION:
 - 1-1.HOUSING: PA66
 - 1-2.CONTACTS: BRASS
 - 2.PLATING SPECIFICATION:
 - 2-1.CONTACTS: TIN/GOLD FLASH PLATED OVER ALL.
 - 3.ELECTRICAL PERFORMANCE:
 - 3-1.CURRENT RATING: 9A
 - 3-2.CONTACT RESISTANCE: 10 mΩ MAX
 - 3-3.INSULATION RESISTANCE: 1000MΩ Min
 - 3-4.DIELECTRIC WITHSTANDING : 1500V
 - 4.ENVIRONMENTAL PERFORMANCE:
 - 4-1.OPERATING TEMPERATURE: -25°C~+85°C.
 - 5.PACKAGE SPEC: REEL
 - 6.P/N:

SERIES NO:

CONNECTOR:

ANGLE:

TYPE:

ROW NO:

PIN Q' PY:

C4201W92-1XX1XX1XXXA3

HOUSING:

COLOR:

PLATING:

TERMIPOINT:

0-UL94V-0

2-UL94V-2

A-BLACK

S-NATURE

C-BRIGHE TIN

1-DIP

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO: C4201W92-1XX1XXX	DWG.NO: ENDE05		
				LINEAR	ANGLES							
A0	NEW RELEASE	21.11.17		0.0±0.35	X'REF±6°	APPROVED	Wang_jr	23.09.08			Pitch 4.2mm 单排 90° DIP Wafer 带定位柱	
A1	DIMENSIONS "B" CHANGE	23.07.25		0.00±0.25	X'±3°	DESIGNER	Han_Gao	23.09.08				
A2	DIMENSIONS CHANGE"6.20"to"6.35	23.08.15	UNIT:mm	0.000±0.10	X*X' ±2°	DRAWN	LX_HOU	23.09.08				
A3	PART NUMBER RENEWAL	23.09.08	SIZE: A4								REV: A3	SHEET: 1/2

1	2	3	4	5	6	7	8
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A



C



E

- F

E

G

H

1	2	3	4	5	6	7	8
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